

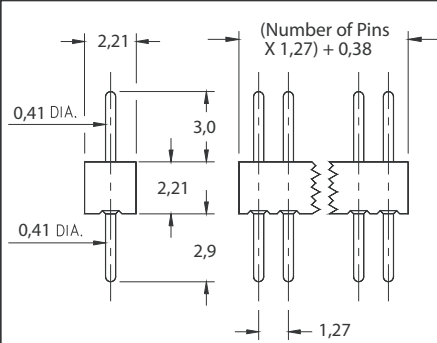


Fig. 1

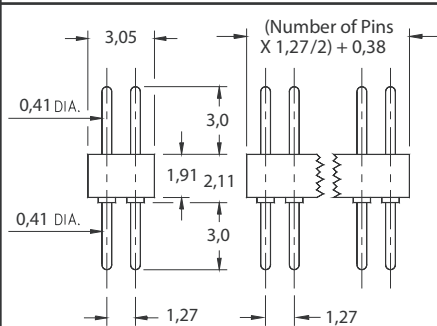


Fig. 2

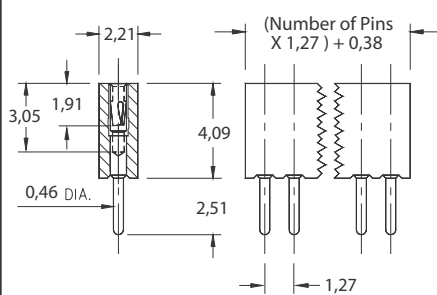


Fig. 3

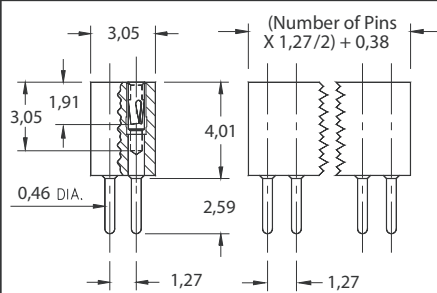


Fig. 4

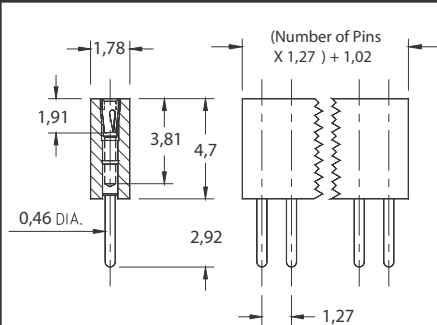
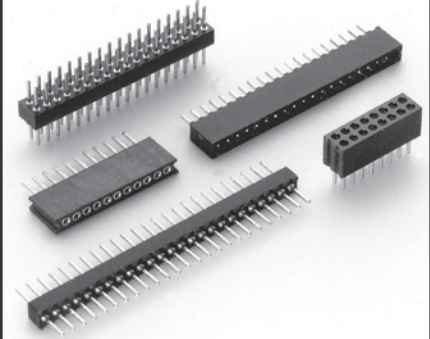


Fig. 5

- Series 850 single and double row interconnects have 1,27 pin spacing & permit board stacking as low as 6,3.
- Pin headers have 0,41 dia. pins (MM #4006-0). See page 166 for details.
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contacts rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 127 and 129 for details.
- Insulators are high temp. thermoplastic, suitable for all soldering operations.



Ordering Information

Fig. 1

Single Row 2,21 Profile Pin Header

850-XX-0__-10-001000

Specify # of pins → 01-50

Fig. 2

Double Row 1,91 Profile Pin Header

852-XX-__-10-001000

Specify # of pins → 002-100



XX= Plating Code See Below

For RoHS compliance select plating code.

SPECIFY PLATING CODE XX=	10	90	40	
Pin Plating	0,25µm Au	5,08µm Sn/Pb	5,08µm Sn	

Fig. 3

Single Row 4,09 Profile Socket

851-XX-0__-10-001000

Specify # of pins → 01-50

Fig. 4

Double Row 4,09 Profile Socket

853-XX-__-10-001000

Specify # of pins → 002-100

Fig. 5

Single Row 4,7 Profile Socket

851-XX-0__-10-002000

Specify # of pins → 01-77



XX= Plating Code See Below

For RoHS compliance select plating code.

SPECIFY PLATING CODE XX=		93	99	43	
Sleeve (Pin)		5,08µm Sn/Pb	5,08µm Sn/Pb		5,08µm Sn
Contact (Clip)		0,76µm Au	5,08µm Sn/Pb		0,76µm Au